

Item	Grade Item	Thermal Conductivity	Hardness (shore00)
1	EVSF100	1.5w/mk	65
2	EVSF500	3.0w/mk	65
3	EVSF600	5.0w/mk	50
4	EVSF600G	6.0w/mk	65
5	EVSF800	8.0w/mk	65
6	EVSF1000	10.0w/mk	65
7	EVSF1200	12.0w/mk	65
8	EVAF800	8.0w/mk	65
9	EVAF100	1.5w/mk	75
10	EVAF500	3.0w/mk	75
11	EVAF600G	6.0w/mk	75
12	EVAF800	8.0w/mk	75
13	EVSA408FG	>0.2w/mk	**
14	EVSC800FG	0.8w/mk	45
15	EVSC800-PI-2-K6	1.1w/mk	90
16	EVSC800-PI-2-K10	1.3w/mk	90
17	EVSC900FG	2.0w/mk	45
18	EVSC900FG-A1	2.0w/mk	45

Item	Grade Item	Thermal Conductivity	Hardness (shore00)
19	EVSC1000FG	3.5w/mk	90
20	EVSF100	1.5w/mk	50
21	EVSF100FG	1.5w/mk	70
22	EVSF100FG-A1	1.5w/mk	90
23	EVSF300	2.0w/mk	60
24	EVSF400	2.5w/mk	60
25	EVSF500	3.0w/mk	75
26	EVSF600	5.0w/mk	75
27	EVSF600G	6.0w/mk	80
28	EVSF800	8.0w/mk	80
29	EVSH600	<0.1w/mk	20
30	EVSP205A	1.0w/mk	**
31	EVSP350P	1.8w/mk	**
32	EVSR600-A-B	1500w/mk	**
33	EVSR600-A-P	1500w/mk	**
34	EVCSF25	25w/mk	**
35	EVSU010-1/2	400w/mk	**
36	EVSU300	0.018w/mk	**

Technical Data Sheet

Product Description

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

EVSF100

Color		Visual
Thickness		ASTM D374
Thermal Conductivity		ASTM D5470
Specific Gravity	2.1g/cc	ASTM D792
Hardness (Shore OO)		ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength		ASTM D412
Electrical Strength		
UL Flammability Rating	UL94 V-0	
Volume Resistivity		ASTM D257
Operating Temperature		--
Thermal Resistance(1mm,@40psi)	0.9°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)		--
Dielectric Constant MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200mm x 300mm

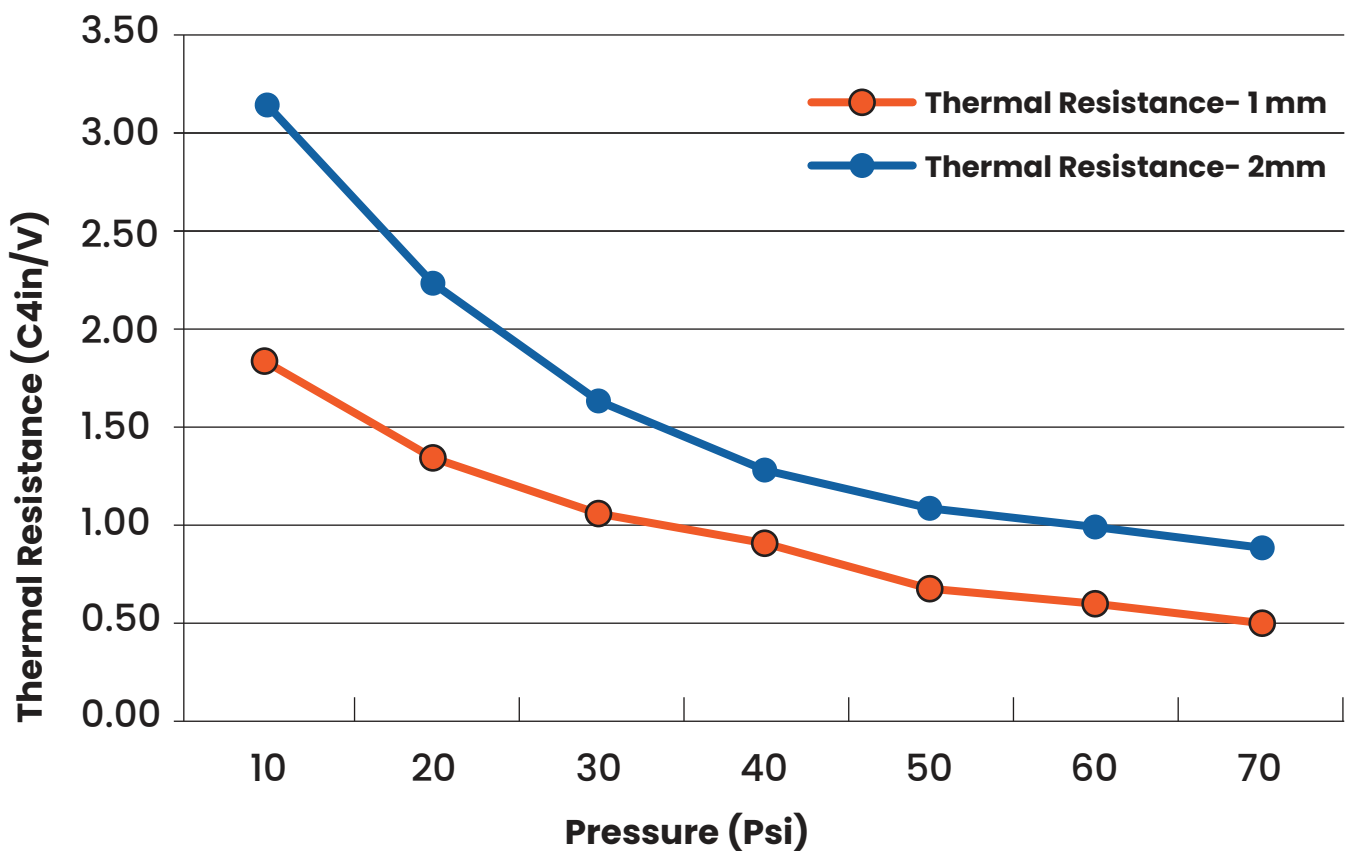
Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

EVSF100

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like:
LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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Technical Data Sheet

Product Description

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

EVSF500

Color		
Thickness		
Specific Gravity		
Thermal Conductivity		
Hardness (Shore OO)	30 - 90	
Elongation	40%	
Tensile Strength	30psi	
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating		--
Volume resistivity	$1 \times 10^{13} \Omega \cdot \text{cm}$	
Operating Temperature	-50 - 200°C	
Thermal Resistance(1mm,@40psi)	$0.45^{\circ}\text{C} \cdot \text{in}^2/\text{W}$	
Compression Ratio(1mm,@40psi)	30%	
Dielectric Constant 1MHz	7.5	
RoHS (10)		
Halogen (4)		
REACH (191)		
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200mm x 300mm

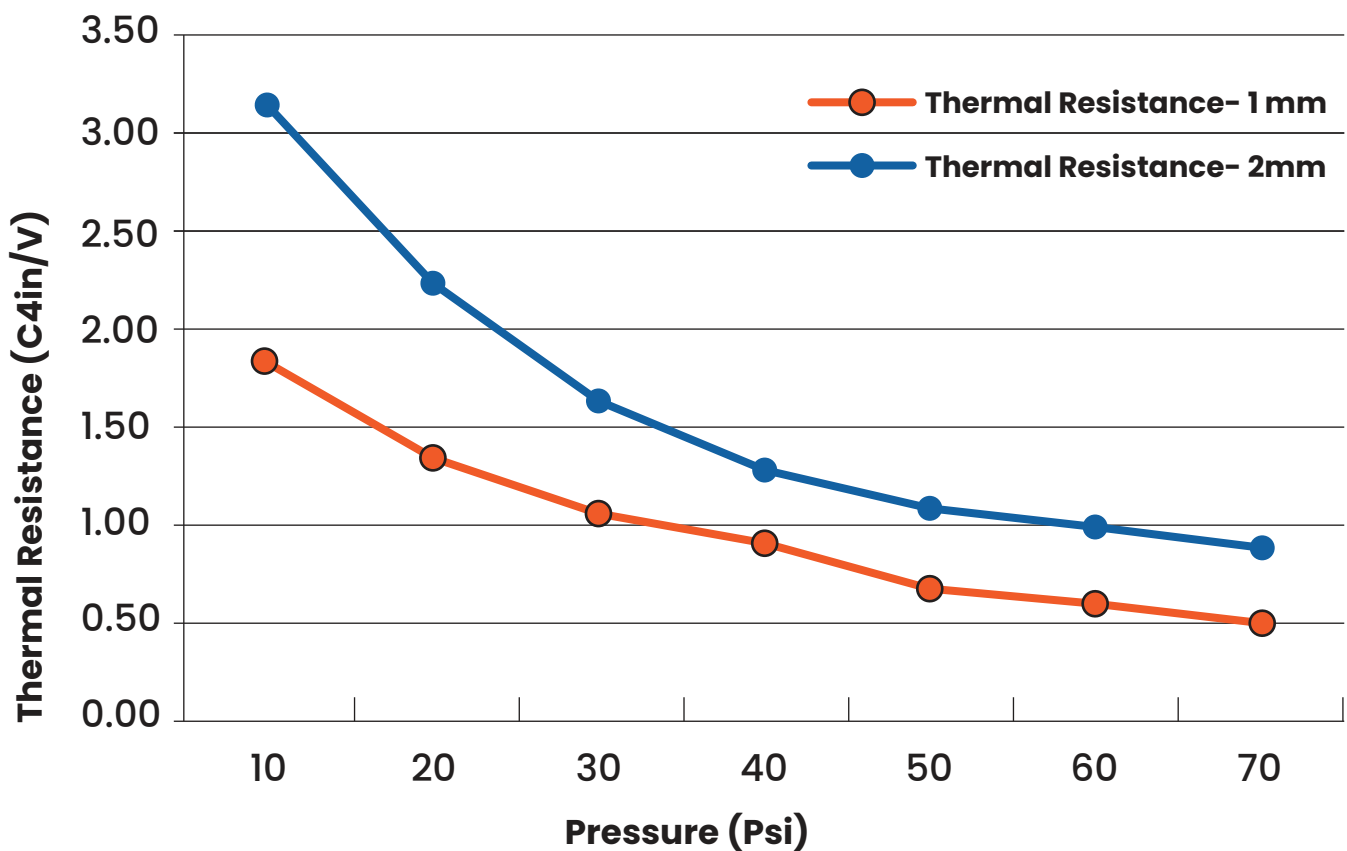
Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

EVSF500

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like:
LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

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Technical Data Sheet

Product Description

EV600 thermal pad are used for filling the two contact surfaces. They are ultra-soft and have good resilience, so effectively exclude air from the contact interface. The products are naturally tacky, can be die-cut into various shapes, easy to operate. The thermal conductivity can reach 5.0 w/m-k.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

EVSF600

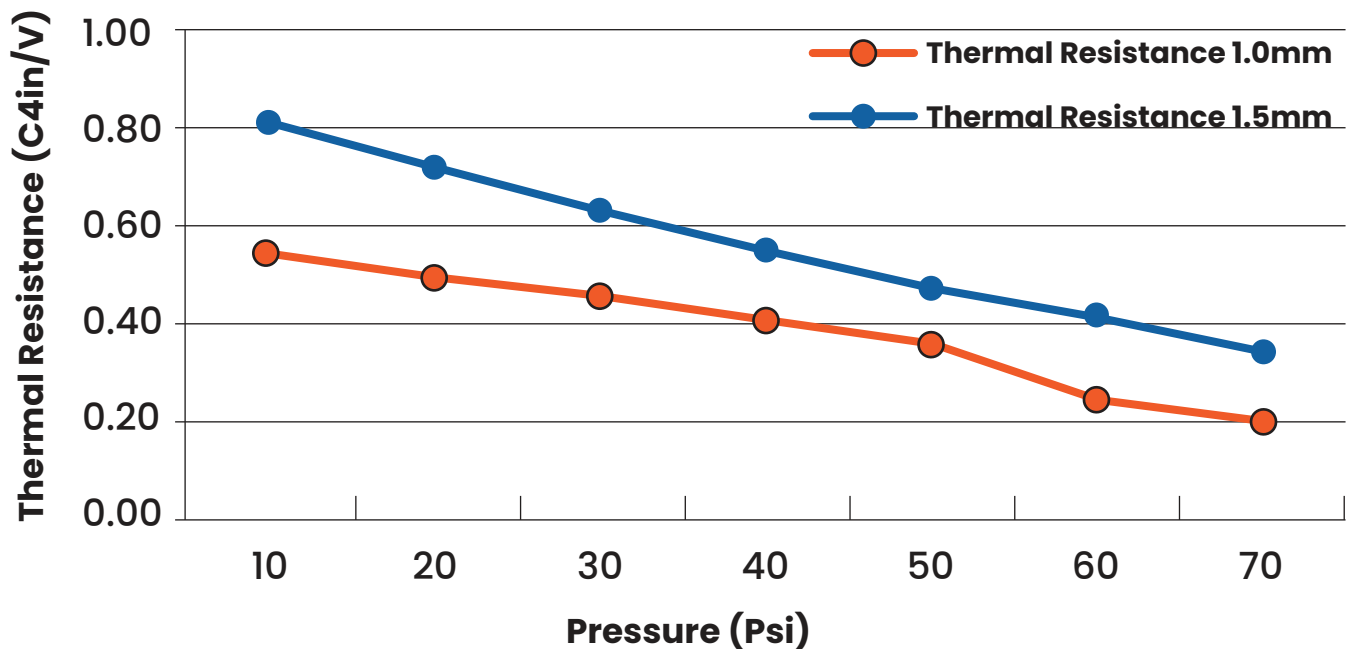
Color	Gray	Visual
Thickness	0.5 - 5.0mm	ASTM D374
Specific Gravity	3.20g/cc	ASTM D792
Thermal Conductivity	5.0 W/m-K	ASTM D470
Hardness (Shore OO)	40-90	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating	UL94 V-0	—
Volume resistivity	$1 \times 10^{13} \Omega \cdot \text{cm}$	ASTM D257
Operating Temperature	-50 - 200°C	—
Thermal Resistance(1mm,@40psi)	0.31°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	25%	—
Dielectric Constant MHz	9	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

EVSF600

Applications

- ✓ Semiconductor heat sink
- ✓ Vehicle navigator
- ✓ Communication & power equipment
- ✓ Graphics card, memory module
- ✓ LED lighting equipment
- ✓ LCD and plasma TV

Thermal Resistance VS Pressure



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All of the above suggestions and data are from information we believe to be accurate. Although provided in good faith, we cannot provide any advice on the application of compatibility because we have no control over the conditions and methods of use of the product. Therefore, these recommendations and data are for reference only and not as a product warranty.

Technical Data Sheet

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations.

EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF600G

Color	Gray	Visual
Thickness	0.5 - 5.0mm	ASTM D374
Specific Gravity	3.30g/cc	ASTM D792
Thermal Conductivity	6.0 W/m-K	ASTM D5470
Hardness (Shore OO)	40-90	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating	UL94 V-0	
Volume resistivity	$1 \times 10^{13} \Omega \cdot \text{cm}$	ASTM D257
Operating Temperature	-50 - 200°	—
Thermal Resistance(1mm,@40psi)	0.29°in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	25%	—
Dielectric Constant MHz	9	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

Product Description

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

EVSF800

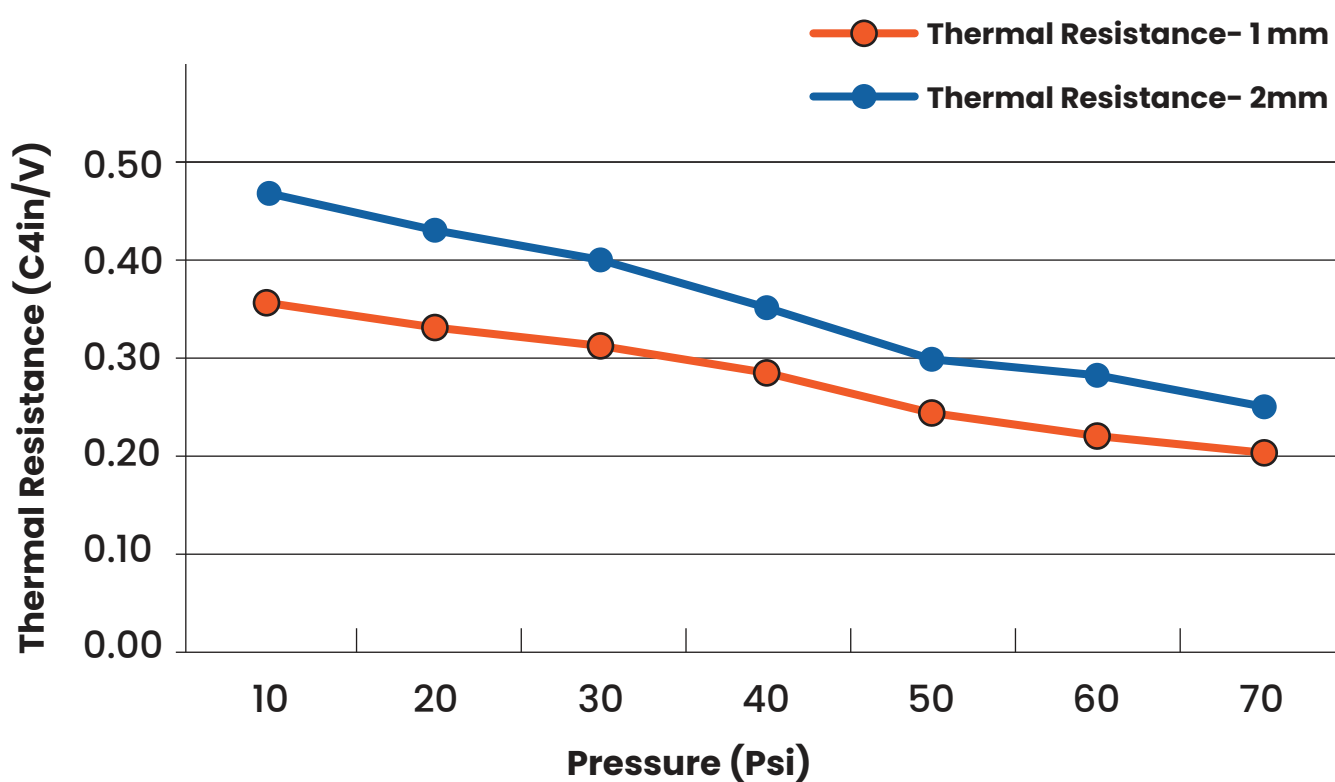
Color		
Thickness		
Specific Gravity		
Thermal Conductivity		
Hardness (Shore OO)	40-80	
Elongation		
Tensile Strength	20psi	
Dielectric Breakdown Voltage	>6KV AC/mm	ASTM D149
UL Flammability Rating		
Volume resistivity		
Operating Temperature		
Thermal Resistance(1mm,@40psi)		
Compression Ratio(1mm,@40psi)		
Dielectric Constant 1MHz		
RoHS (10)		
Halogen (4)		
REACH (191)		
Standard Sheet Size		200 x 300mm
(Note: Other sheet sizes may be available upon request.)		

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like:
LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF800

Thermal Resistance VS Pressure



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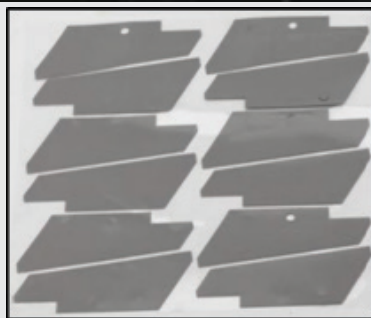
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Technical Data Sheet

Product Description

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

EVSF1000

Color	Gray	Visual
Thickness	0.5 - 5.0mm	ASTM D374
Specific Gravity	3.40g/cc	ASTM D792
Thermal Conductivity	10.0 W/m-K	ASTM D5470
Hardness (Shore OO)	40-80	ASTM D2240
Elongation	15%	ASTM D412
Tensile Strength	10psi	ASTM D412
Breakdown voltage strength	>6KV AC/mm	ASTM D149
UL Flammability Rating	UL94 V-0	
Volume resistivity	$1 \times 10^{12} \Omega \cdot \text{cm}$	ASTM D257
Operating Temperature	-50 - 150°C	—
Thermal Resistance(1mm,@40psi)	0.12°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	30%	—
Dielectric Constant MHz	12	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size		200 x 300mm
(Note: Other sheet sizes may be available upon request.)		

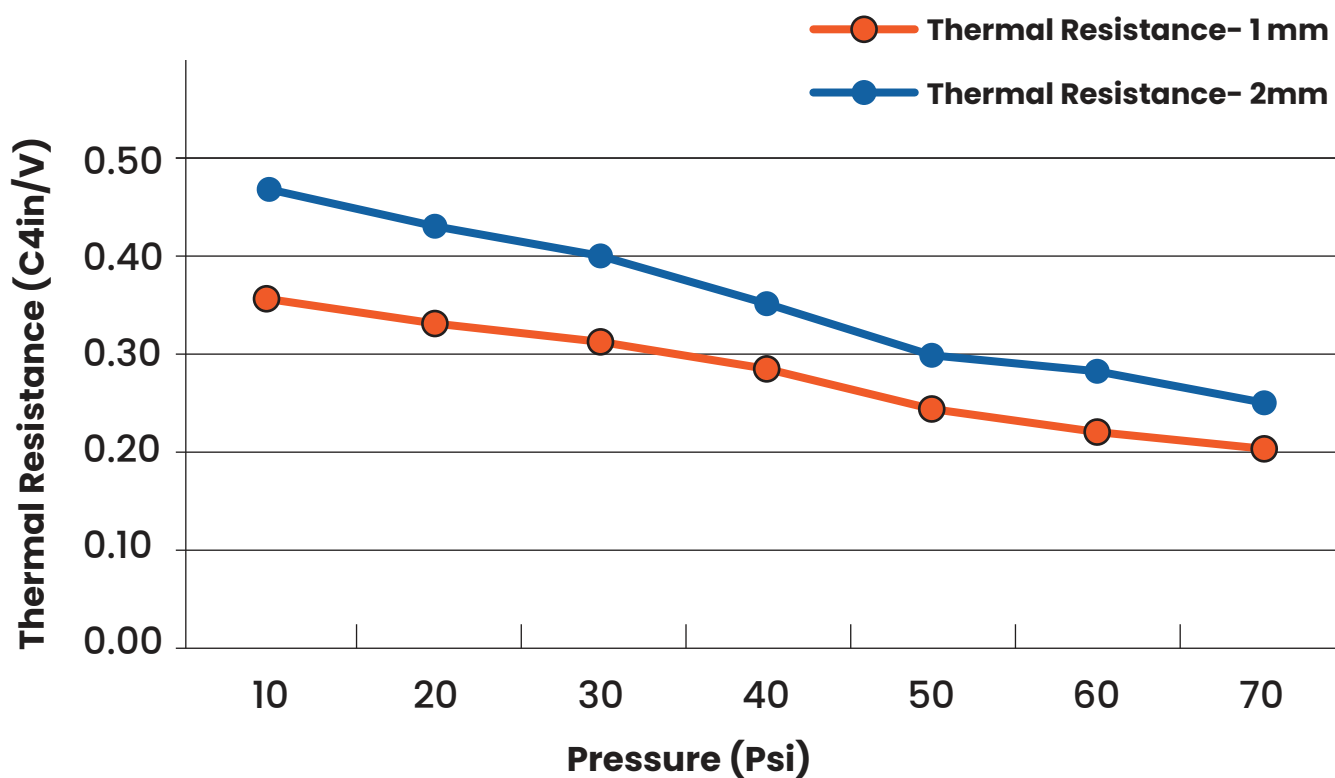
Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

EVSF1000

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like:
LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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Technical Data Sheet

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF1200

Color	Gray	Visual
Thickness	0.8 - 5.0mm	ASTM D374
Specific Gravity	3.40g/cm ³	ASTM D792
Thermal Conductivity	12.0 W/m.k	ASTM D5470
Hardness(Shore oo)	40-80	ASTM D2240
Elongation	15%	ASTM D412
Tensile Strength	10psi	ASTM D412
Breakdown Voltage Strength	>5KV AC/mm	ASTM D149
UL Flammability Rating	UL94 V-0	—
Volume Resistivity	1*10 ¹² Ω.cm	ASTM D257
Operating Temperature	-50 - 120°C	—
Thermal Resistance(1mm,@40psi)	0.1°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	≥15%	—
Dielectric Constant MHz	12.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size		200 x 300mm
(Note: Other sheet sizes may be available upon request.)		

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EverTherm non-silicone thermal pads are manufactured from an advanced resin. They will not damage or promote circuit failure and have no siloxane volatilization resulting in no silicone oil seeping. EverTherm Non Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVAF800 NON-SILICONE

Color	Light Gray	Visual
Thickness	0.5 - 5.0mm	ASTM D374
Specific Gravity	3.4g/cm ³	ASTM D792
Thermal Conductivity	8.0 W/m.k	ASTM D5470
Hardness(Shore 00)	45-80	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltage	>8KV/mm	ASTM D149
Flammability Rating	94 V-0	UL 94
Volume Resistivity	10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-40-120°C	--
Thermal Resistance(1mm,@40psi)	0.10°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	20%	--
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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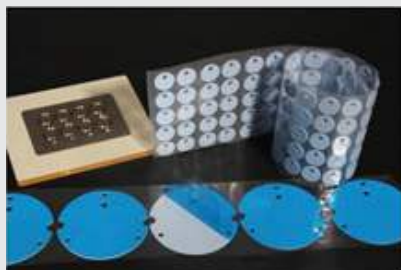
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Technical Data Sheet

EVAF100 non-silicone thermal gap pads are manufactured from highly Engineered resins. EVAF100 non-silicone thermal gap pads will not create circuit failure as they contain no siloxane volatilization, therefore will not promote silicone oil seeping. EVAF100 Non-Silicone thermal gap pads have excellent tensile strength and wear resistance. EverTherm Non-Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Applications

- ✓ Power battery pack
- ✓ Vehicle navigator
- ✓ Optical precision equipment
- ✓ Camera equipment
- ✓ Notebook computer
- ✓ Mobile and communication equipment
- ✓ Automotive engine control equipment
- ✓ High end industrial control and medical electronics



EVAF100 SILICONE FREE

Color	White	Visual
Thickness	0.25 - 5.0mm	ASTM D374
Specific Gravity	1.9g/cm ³	ASTM D792
Thermal Conductivity	1.0 W/mK	ASTM D5470
Hardness(shore oo)	40-80	ASTM D2240
Elongation	100%	ASTM D412
Tensile Strength	75psi	ASTM D412
Dielectric Breakdown Voltage	>8KV/AC/mm	ASTM D149
Flammability Rating	94 V-0	UL 94
Volume Resistivity	10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-40 - 130°C	—
Thermal Resistance(1mm,@40psi)	1.10°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	30%	—
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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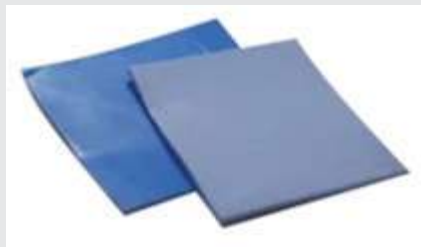
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Technical Data Sheet

EVAF500 non-silicone thermal gap pads are manufactured from highly Engineered resins. EVAF500 non-silicone thermal gap pads will not create circuit failure as they contain no siloxane volatilization, therefore will not promote silicone oil seeping. EVAF500 Non-Silicone thermal gap pads have excellent tensile strength and wear resistance. EverTherm Non-Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Applications

- ✓ Power battery pack
- ✓ Vehicle navigator
- ✓ Optical precision equipment
- ✓ Camera equipment
- ✓ Notebook computer
- ✓ Mobile and communication equipment
- ✓ Automotive engine control equipment
- ✓ High end industrial control and medical electronics



EVAF500 NON-SILICONE

Color	Off White	Visual
Thickness	0.25 - 5.0mm	ASTM D374
Specific Gravity	2.9g/cm ³	ASTM D792
Thermal Conductivity	3.0 W/mK	ASTM D5470
Hardness(Shore oo)	40-80	ASTM D2240
Elongation	70%	ASTM D412
Tensile Strength	55psi	ASTM D412
Dielectric Breakdown Voltage	>8KV/AC/mm	ASTM D149
Flammability Rating	94 V-0	UL 94
Volume Resistivity	10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-40 - 130°C	---
Thermal Resistance(1mm,@40psi)	0.6°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	30%	---
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EverTherm non-silicone thermal pads are manufactured from an advanced resin. They will not damage or promote circuit failure and have no siloxane volatilization resulting in no silicone oil seeping. EverTherm Non Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devises & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVAF600G NON-SILICONE

Color	White	Visual
Thickness	0.5-5.0mm	ASTM D374
Specific Gravity	3.1g/cm3	ASTM D792
Thermal Conductivity	6.0 W/m.k	ASTM D5470
Hardness(shore 00)	45-80	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	30Psi	ASTM D412
Dielectric Breakdown Voltage	>8KV/mm	ASTM D149
Flammability Rating	94 V-0	UL
Volume Resistivity	10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-40 - 125°C	---
Thermal Resistance(1mm,@40psi)	0.25°C*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)	20%	---
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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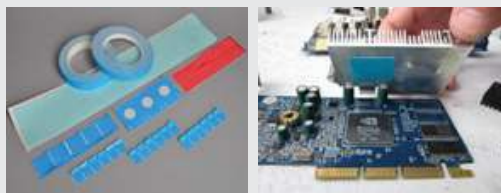
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Technical Data Sheet

EverTherm thermal tape is widely used in bonding heat sinks to microprocessors and power consuming semiconductors. It features a high adhesive strength and low thermal impedance, which can effectively replace silicone grease and mechanical fixation.



Material Properties

- High-strength viscosity suitable for various surfaces
- Double-sided pressure-sensitive adhesive tape
- High thermal conductive acrylic adhesive
- Can withstand long-term high temperature working environment

Applications

- ✓ LED lighting products
- ✓ Chassis, frame or other cooling components
- ✓ Large capacity drive
- ✓ Heat pipe assembly
- ✓ RDRAM memory
- ✓ High frequency micro processing chip
- ✓ Notebook and desktop computers



EVSA408FG

Color	White	Visual
Substrate	Acrylic resin (Acrylic)	***
Substrate reinforcement	Fiberglass	***
Thickness(mm)	0.20±0.01	ASTM D374
Dielectric Breakdown Voltage@AC	>4000V	ASTM D149
Release force	1.8kg/25mm	PSTC-3
Shear strength1.0 kg loading on 25 mm x 25 mm	> 48 hrs	PSTC-7
Heat resistance0.5kg loading on 25mm x 25mm at 80	> 24 hrs	***
Thermal conductivity (W/m.k)	1.0	ASTM D5470
Operating temperature		***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sizes may be available upon request)	1024mmx50m	

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

Product Description

EVSC800FG is made of ultra-thin fiberglass coated with thermally conductive silicone on one side. The overall total thickness is 0.1 mm and acts as a heat transfer as it breaks down voltage.



Benefits

- High thermal conductivity, low resistance
- Electrical insulation
- High pressure resistance
- High tensile strength

Applications

- ✓ Power adapter
- ✓ Automobile electronics
- ✓ Communication equipment
- ✓ Motor controllers
- ✓ High pressure interface
- ✓ Semiconductor optoelectronic products



EVSC800FG Thermal Film

Color	Gray	Visual
Composition	Thermal conductive silicone, glass fiber	* * *
Thickness (mm)	0.2-0.5mm	ASTM D751
Density (g/cc)	2.2	ASTM D297
Hardness (Shore A)	45	ASTM D2240
Tensile strength (MPa)	450	ASTM D412
Operating Temperature°F/ °C	(-58 to 356°F) / (-50 to 200°C)	* * *
Electrical		
Breakdown Voltage(AC KV/mm)	>5000	ASTM D149
Dielectric constant (1000 Hz)	5.5	ASTM D150
Volume resistivity	5.0 X 10 ¹³	ASTM D257
(ohm-meter)		
Flame Rating	V0	UL 94
Thermal conductivity		
Thermal Conductivity(W/m-K)	0.8	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm X 305mm

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Technical Data Sheet

Product Description

EVSC800-PI-2-K6 is made of ultra-thin PI film and coated with thermally conductive silicone on one side. The overall total thickness is 0.16 mm and acts as a heat transfer as it breaks down voltage.



Benefits

- High thermal conductivity, low resistance
- Electrical insulation
- High pressure resistance
- High tensile strength

Applications

- ✓ Power adapter
- ✓ Automobile electronics
- ✓ Communication equipment
- ✓ Motor controllers
- ✓ High pressure interface
- ✓ Semiconductor optoelectronic products



EVSC800-PI-2-K6 Thermal Film

Color	Gray	Visual
Composition	PI film, thermal silicone	* * *
Thickness (mm)	0.16±0.02	ASTM D751
Density (g/cc)	2.2	ASTM D297
Hardness (Shore A)	90±5	ASTM D2240
Tensile strength (MPa)	35	ASTM D412
Operating Temperature°F/ °C	-50 to 200°C	* * *
Electrical		
Breakdown Voltage(AC KV/mm)	>6000	ASTM D149
Dielectric constant (1000 Hz)	5.0	ASTM D150
Volume resistivity	10 ¹²	ASTM D257
(ohm-meter)		
Flame Rating	V-0	UL 94
Thermal conductivity		
Thermal Conductivity(W/m-K)	1.1	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm x 305mm

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Technical Data Sheet

Product Description

EverTherm thermally conductive insulating pads are made of an ultra-thin Polyimide film coated with a thermally conductive silicone on both sides. The overall total thickness is 0.1 mm and acts as a heat transfer as it breaks down voltage.



Benefits

- High thermal conductivity, low resistance
- Electrical insulation
- High pressure resistance
- High tensile strength

Applications

- ✓ Power adapter
- ✓ Automobile electronics
- ✓ Communication equipment
- ✓ Motor controllers
- ✓ High pressure interface
- ✓ Semiconductor optoelectronic products



EVSC800-PI-2-K10 Thermal Insulating Pad

Color	Yellow	Visual
Composition	PI film, thermal silicone	* * *
Thickness (mm)	0.16±0.02	ASTM D751
Density (g/cc)	2.3	ASTM D297
Hardness (Shore A)	90±5	ASTM D2240
Tensile strength (MPa)	35	ASTM D412
Operating Temperature°F/ °C	-50 to 200°C	* * *
Electrical		
Breakdown Voltage(AC KV/mm)	>6000	ASTM D149
Dielectric constant (1000 Hz)	3.7	ASTM D150
Volume resistivity	10 ¹²	ASTM D257
(ohm-meter)		
Flame Rating	V-0	UL 94
Thermal conductivity		
Thermal Conductivity(W/m-K)	1.3	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm x 305mm

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Technical Data Sheet

EverTherm SC Series is a thermally conductive silicone tape offering high temperature capability and conformability. Fiberglass fabric supports the thermally conductive silicone rubber impregnation and adds dimensional stability and puncture resistance. This thin material keeps thermal resistance low and save space while providing electrical isolation.



Material Properties

- Assembly time reduced by 70% over grease & mica systems
- Puncture resistance; high thermal conductivity
- Electrically isolates power sources from heat sink devices
- Resists high pressure and deterioration
- Optional Adhesive available for ease of install
- UL94V-0 flammability rating, ROHS, halogen free
- Easy to assemble

Applications

- ✓ Automotive electronics
- ✓ Adapter
- ✓ Communication equipment
- ✓ Motor Controller
- ✓ High pressure interface
- ✓ Semiconductor Optoelectronic Products



EVSC900FG

Color	Brick Red	Visual
Base	Fiberglass	* * *
Thickness (mm)	0.2-0.5mm	ASTM D751
Density (g/cm ³)	2.2	ASTM D297
Hardness (Shore A)	45	ASTM D2240
Tensile Strength (psi)	450	ASTM D412
Applicable tempure/ °C	-50 to 200°C	* * *
Electrical		
Dielectric Breakdown Voltage@AC	>4000V	ASTM D149
Dielectric constant (1MHz)	5.5	ASTM D150
Volume resistivity (Ω.cm)	5.0 X 10 ¹³	ASTM D257
Fire rating	V-0	UL 94
Thermal conductive		
Thermal conductivity(W/m.k)	2.0	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm x 305mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

Product Description

Thermal Insulating Sheet



Material Properties

- High thermal conductivity, low resistance
- Electrical insulation
- High pressure resistance
- High tensile strength

Also Available:

- Cut per drawing and custom shapes
- Optional adhesive

Applications

- ✓ Automotive electronics
- ✓ Adapter
- ✓ Communication equipment
- ✓ Motor Controller
- ✓ High pressure interface
- ✓ Semiconductor Optoelectronic Products



EVSC1000FG

Color	White	Visual
Composition	Fiber glass	* * *
Thickness (mm)	0.2-0.5mm	ASTM D751
Hardness (Shore A)	90	ASTM D2240
Pressure (Psi)	10	100 200
(°C*in2/W)	0.59	0.29 0.24
Applicable temp ^{°F} /°C	-50 to 200°C	* * *
Electrical		
Dielectric Breakdown Voltage@AC	>4000V	ASTM D149
Dielectric constant (1MHz)	3.0~3.5	ASTM D150
Volume resistivity (Ω.cm)	10 ¹¹	ASTM D257
Fire rating	V0	UL 94
Thermal conductive		
Thermal conductivity(W/m.k)	3.5	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)	305mm x 305mm	

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EVSF100LFG is a tough, wear-resistant, tensile-strength, thermally conductive silicone pad that is used to fill two pressure-sensitive or vibrating interfaces to allow air to escape from the interface and improve thermal conductivity. The product is self-adhesive and can be die cut into various shapes for easy assembly. Thermal conductivity is 1.0W/MK.



Material Properties

- Semiconductor heat sink
- Vehicle navigator
- Communication & power equipment
- Graphics card, memory module
- LED lighting equipment
- LCD and plasma TV



EVSF100FG

Color	White	Visual
Thickness	0.3 - 10.0mm	ASTM D374
Specific Gravity	2.2g/cc	ASTM D792
Thermal Conductivity	1.0 W/m-K	ASTM D5470
Hardness (Shore OO)	50-75	ASTM D2240
Elongation	4%	ASTM D412
Tensile Strength	130psi	ASTM D412
Electrical Strength	>200VAC/mil	ASTM D149
UL Flammability Rating	UL94 V-0	
Volume resistivity	7*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 - 200°C	---
Thermal Resistance(1mm,@40psi)	1.0°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	20%	---
Dielectric Constant MHz	NA	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations.

EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF300

Color	Gray	Visual
Thickness	0.15 - 15.0mm	ASTM D374
Specific Gravity	2.3g/cc	ASTM D792
Thermal Conductivity	2.0 W/m-k	ASTM D5470
Hardness(Shore oo)	30-90	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	40psi	ASTM D412
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating	UL94 V-0	---
Volume resistivity	1*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 - 200°C	---
Thermal Resistance(1mm,@40psi)	0.7°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	40%	---
Dielectric Constant MHz	6.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF400

Color	Yellow	Visual
Thickness	0.15 - 10.0mm	ASTM D374
Specific Gravity	2.7g/cm ³	ASTM D792
Thermal Conductivity	2.50 W/mk	ASTM D5470
Hardness(Shore oo)	30-90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	40%	ASTM D412
Tensile Strength	30psi	ASTM D412
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 - 200°C	— —
Thermal Resistance(1mm,@30psi)	0.5°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	— —
Dielectric Constant@1 MHz	7.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		200 x 300mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EverTherm SH series is a highly sustainable and extremely versatile material. This product has uniform foam structure, excellent abrasion resilience, will not break down over time and is flame retardant. It can also be used for sound & heat insulation, moisture barrier, shock absorption, primarily for communications, electric vehicle (EV) power and electronics industries.



Material Properties

- Excellent flame retardancy
- Good electrical insulation
- Excellent elasticity high very low compression set
- Extreme temperature resistance, good sealing
- Will not break down over time

Applications

- ✓ Communications,
- ✓ Electric Vehicle energy
- ✓ Electronics,
- ✓ Lighting equipment cabinet
- ✓ Hardware and other fields



EVSH600

Parameter	Unit	Test Standard
Color	Visual	Gray
Thickness	mm	1.0-12
Density (25°C)	g/cm ³	0.45
Hardness	shore C	5-85, Common 15/20
Substrate	Silicone	
Compression deformation (maximum)	%	70°C<1, 100°C<5
Compression stress	65kPa	ASTM D1056/compress 25% stress
Elongation	%	80
Flammability	UL94	V-0
Flame spread index	Is	25
Vapor Density	Ds	Test in 4min < 50 Test in 1.5min < 20
Toxic gas diffusion level	SMP-800C	PASS
Water absorption (Room temperature 24hr)	%	1.4
Dielectric constant	1kHz	1.42
Dielectric strength	KV/mm	3.58
Dry arc resistance	s	92
Volume resistivity	Ω•cm	1015
Thermal conductivity	W/m.k	< 0.1
Low temperature deflection (-55°C)	ASTM D 1056	PASS
Recommend temperature	°C	-55 ~ 220
Recommended maximum temperature for intermittent use	°C	250
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		300mm x 400mm

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Technical Data Sheet

Phase Change Material (PCM)

EverTherm PCM Series is very soft and shapeable and exhibits excellent thermal conductivity in the vertical (z-plane) direction. This material is a solid material at room temperature. When exposed to 50-55°C it becomes a soft semi-flowing paste. This allows easy shaping conformation between 2 compressed surfaces. The material will return back into solid state when it reaches below 50-55°C temperature. It can also be customized into different shapes and sizes based on the requirements of the application.



Material Properties

- Excellent thermal conductivity in the vertical z-plane
- Strong interface wetting ability, long-term reliable thermal conductivity
- Good flexibility & compression ratio
- Effectively reduce the coating thickness of the material between the interface
- Flexible and can be easily converted to custom sizes
- Thin and lightweight

Applications

- ✓ Semiconductor device testing,
 - CPU, GPU, MCM
 - Mobile phones & PC tablets, PCs, Servers, and cloud storage
- ✓ PDP, LED devices, IGBT Modules
- ✓ Optical communications equipment, medical equipment
- ✓ High frequency microprocessor
- ✓ Integrated Chip



EVSP205A

Item	Detection	Testing method
Color	Gray	Visual
Thickness(mm)	0.13mm	ASTM D751
Thickness tolerance	±0.015mm	ASTM D751
Density/cm ³	2.85	ASTM D297
Applicable temp	-40°C - 125°C	***
Phase change temperature	50°C - 55°C	***
Volume Resistance (Ω.cm)	2.0 X 10 ¹⁰	ASTM D257
Thermal conductivity (W/m.K)	3.0	ASTM D5470
Dielectric constant(1MHZ)	3.0	ASTM D150
Thermal impedance@10psi(°C*in ² /W)	0.05	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm x 305mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

Phase Change Material (PCM)

EverTherm PCM Series is very soft and shapeable and exhibits excellent thermal conductivity in the vertical (z-plane) direction. This material is a solid material at room temperature. When exposed to 50-55°C it becomes a soft semi-flowing paste. This allows easy shaping conformation between 2 compressed surfaces. The material will return back into solid state when it reaches below 50-55°C temperature. It can also be customized into different shapes and sizes based on the requirements of the application.



Material Properties

- Excellent thermal conductivity in the vertical z-plane
- Strong interface wetting ability, long-term reliable thermal conductivity
- Good flexibility & compression ratio
- Effectively reduce the coating thickness of the material between the interface
- Flexible and can be easily converted to custom sizes
- Thin and lightweight

Applications

- ✓ Semiconductor device testing,
 - CPU, GPU, MCM
 Mobile phones & PC tablets, PCs, Servers, and cloud storage
- ✓ PDP, LED devices, IGBT Modules
- ✓ Optical communications equipment, medical equipment
- ✓ High frequency microprocessor
- ✓ Integrated Chip



EVSP350P

Item	Detection	Testing method
Color	Green	Visual
Reinforcement Carrier	**	***
Thickness (mm)	0.20-0.50	ASTM D374
Elongation (%) Elongation	40	ASTM D882A4
Tensile strengthTensile Strength (Psi)	7100	ASTM D882A4
Continuous Operating temperaturep(°C)	257	***
Phase Change Temp(°C)	55	ASTM D3418
Dielectric Breakdown Voltage(Vac)	8KV	ASTM D149
Dielectric constant(1MHz)	4.5	ASTM D150
Volume resistivity(Ω)	1012	ASTM D257
Thermal conductivity(W/m.k)	1.8	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		305mm x 305mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

Product Description

EverTherm EVSR600-A-B Graphite Sheet is a synthetic graphite film with a unique layered structure and crystal orientation with super-conductivity in the planar direction. This high performing versatile material is wrapped with a white PET film which can be converted or cut into various shapes.



Applications

- ✓ Applications
- ✓ Mobile phones
- ✓ Notebook / Laptop Computers
- ✓ TV
- ✓ Thermal module
- ✓ Routers



EVSR600-A-B

Item		Test method
Protective film color		Visual
Total thickness (mm)		ASTM D374
Graphite substrate thickness (mm)		ASTM D374
Ingredient		***
Insulating adhesive tape		***
Density (g/cm ³)		ASTM D792
Thermal Conductivity @XY(W/m.k)		ASTM E1461
Thermal Conductivity @Z(W/m.k)		ASTM E1461
Heat (J/g.k)		***
Proper temperature (°C)		***
RoHS		IEC 62321
Halogen		EN14582
REACH		EN14372
Standard Sheet Size	150 x 150mm	

(Note: Other sheet sizes may be available upon request.)

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EverTherm CS series is a composite material which offers extremely high thermal conductivity, low density and good durability. Carbon fiber is an anisotropic and offering a very high level of thermal conductivity in the Z axis. This silica gel sheet is very soft and well compressed, it is used to fill the interface of two substrates, ensuring air from the interface is discharged, and heat conduction dramatically improved. Thermal conductivity @ 25.0W/M.K



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good flexibility and high compression ratio

Adhesive optional:

- A1 equals single-sided adhesive
- A2 equals double-sided adhesive

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVCSF25

Color	Black	Visual
Thickness	0.5 - 20.0mm	ASTM D374
Metal	Silicone	***
Filler	Carbon Fiber	***
Density	2.9g/cm3	ASTM D792
Thermal Conductivity	25.0W/m.k	ASTM D5470
Dielectric Breakdown Voltage@AC	100V	ASTM D149
Hardness (Shore 00)	40-90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Thermal Resistance(1mm,@40psi)	0.06°C*in2/W	ASTM D5470
Operating Temperature(°C)	-50 - 160°C	ASTM D1329
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size (Note: Other sheet sizes may be available upon request.)		100 x 150mm

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Technical Data Sheet

EverTherm SY series is a new type of aerogel thermal insulation film which is a thin-film nano thermal insulation material. Aerogel is the world's lightest solid material offering the best thermal insulation performance. Its pore diameter is ~ 20nm, which is smaller than the free path of air (70nm). The air molecules in the pores lose their ability to flow freely, thus achieving ultra-high thermal insulation performance. In addition, by using the heat insulation film and the heat dissipation film in combination, the uniformity of the heat insulation can be improved. For related information, please consult the CR Technology technical team.



Material Properties

- Thin film: 80µm ~ 350 µm
- The combined use of heat dissipation film can provide a variety of thermal solutions.

Applications

- ✓ Wearable terminal
- ✓ Smart phone
- ✓ LCD TV
- ✓ Tablet PC
- ✓ Digital cameras and various electronic devices that require heat insulation



EVSY300

Item	Detection	Testing method
Thickness	80µm ;130µm 350µm	ASTM D751
Substrate (Base)	non	***
Thermal conductivity (W/(m·K))		ASTM D5470
Operating temperature range (°C)		***
Long-term heat resistance temperature (°C)	120	ASTM D2240
Flame Rating	Not flame retardant	***
Standard Sheet Size		***
<i>Note: Other sheet sizes may be available upon request.</i>		
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.